

Title (en)
INTEGRATED CIRCUIT WITH INTERNAL IMPEDANCE MATCHING CIRCUIT

Title (de)
INTEGRIERTE SCHALTUNG MIT INTERNER IMPEDANZANPASSUNGSSCHALTUNG

Title (fr)
CIRCUIT INTEGRE AVEC CIRCUIT D'ADAPTATION D'IMPEDANCE INTERNE

Publication
EP 1502309 A1 20050202 (EN)

Application
EP 03750119 A 20030508

Priority
• US 0314893 W 20030508
• US 14225002 A 20020509
• US 42733003 A 20030501

Abstract (en)
[origin: WO03096439A1] An integrated circuit package (100) houses an connects to a die to form an integrated circuit (104) with internal matching (106). The package comprises a lead frame comprising at least one transmission line, a die paddle, and at least one input lead and at least one output lead (102). Bond wires connect select locations along the at least one transmission line to ground through impedance matching network (106) associated with at least one of the output leads. The package may also substantially encapsulate the lead frame, while exposing the die paddle and the input/output leads.

IPC 1-7
H01L 39/00

IPC 8 full level
H01L 21/822 (2006.01); **H01L 23/31** (2006.01); **H01L 23/495** (2006.01); **H01L 23/50** (2006.01); **H01L 23/552** (2006.01); **H01L 23/66** (2006.01); **H01L 27/04** (2006.01); **H03F 1/56** (2006.01); **H01L 23/522** (2006.01)

CPC (source: EP KR)
H01L 23/3107 (2013.01 - EP); **H01L 23/49517** (2013.01 - EP); **H01L 23/49541** (2013.01 - EP); **H01L 23/49575** (2013.01 - EP); **H01L 23/49589** (2013.01 - EP); **H01L 23/50** (2013.01 - EP); **H01L 23/552** (2013.01 - EP); **H01L 23/64** (2013.01 - KR); **H01L 23/66** (2013.01 - EP); **H01L 24/06** (2013.01 - EP); **H01L 24/49** (2013.01 - EP); **H10N 60/00** (2023.02 - KR); **H01L 23/5223** (2013.01 - EP); **H01L 23/5227** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 2224/05553** (2013.01 - EP); **H01L 2224/05599** (2013.01 - EP); **H01L 2224/0603** (2013.01 - EP); **H01L 2224/32245** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/48247** (2013.01 - EP); **H01L 2224/48253** (2013.01 - EP); **H01L 2224/49111** (2013.01 - EP); **H01L 2224/49171** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/85447** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01014** (2013.01 - EP); **H01L 2924/01029** (2013.01 - EP); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/01082** (2013.01 - EP); **H01L 2924/10253** (2013.01 - EP); **H01L 2924/10329** (2013.01 - EP); **H01L 2924/14** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP); **H01L 2924/18301** (2013.01 - EP); **H01L 2924/19041** (2013.01 - EP); **H01L 2924/19042** (2013.01 - EP); **H01L 2924/19105** (2013.01 - EP); **H01L 2924/30105** (2013.01 - EP); **H01L 2924/3011** (2013.01 - EP); **H01L 2924/30111** (2013.01 - EP)

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DE FR GB

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